THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:		§	Patent No.:	7205178 B2		
Hei Ming SHIU et al		§ §	Issue Date:	April 17, 2007		
•		§				
Application No.: 10/807527		§	Examiner:	Thanh Y. Tran		
		§				
Filed:	March 24, 2007	§	Group Art Unit: 2822			
		§ §	Docket No.:	SC13154HP		
		Ü				
Title:	Title: LAND GRID ARRAY PACKAGED DEVICE ANDMETHOD OF FORMING SAI					
	Certificate of Submission					
		I hereby certify that this correspondence is being submitted to the U.S.P.T.O., Alexandria, VA.				
	Addressed per 37 C.F.R.§ 1.1(a) and deposited with the United States Postal Service with sufficient postage as first class mail. Facsimile transmitted in accordance with 37 C.F.R.§1.6(d).					
	X Submitted electronically via EFS in accordance with "Legal Framework for EFS Web".					
	5 July 2007					
	Date of Submission					
	Signature					
			Jeslyn GOH			
		Printed Name of Person Signing Certificate				

Commissioner for Patents Alexandria, VA 22313

SUBMISSION OF CERTIFICATE OF CORRECTION

Dear Commissioner:

Enclosed, in duplicate, is a Certificate of Correction listing error(s) in the subject patent. Please enter these corrections. Since the errors appear to be on the part of the United States Patent Office, there should be no charge.

7/5/07

Respectfully submitted,

Charles Bergere

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APPLICATION NO:

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DATE:

04/17/2007

INVENTOR(S):

Hei Ming SHIU et al

It is certified that errors appear in the above-identified patent and that said Letters Patent are hereby corrected as shown below:

In Column 6, Line 54, Claim No. 15:

Change "wherein-squashed" to - -wherein squashed- -

In Column 6, Line 56, Claim No. 15:

Change "s-aid" to - -said- -

MAILING ADDRESS OF SENDER

Freescale Semiconductor, Inc. Law Department 7700 West Parmer Lane PL02 Austin, TX 78729